

WHAT IS CLAIMED IS:

1. A mold die comprising a first die having a recess in a predetermined form and a second flat die, said mold die being for
5 disposing said first die on a surface of a wiring board which has a plurality of openings and bears a semiconductor chip via an elastic material, which surface bears said semiconductor chip, and for disposing said second die on a back of said surface of said wiring board which bears said semiconductor chip, and for sealing with an insulating resin a periphery of
10 said semiconductor chip and at least one of said openings of said wiring board, wherein
said second die comprises a protrusion around an area overlapping said opening sealed with said insulating resin.
- 15 2. A method for manufacturing a semiconductor device by sealing, by transfer mold using a die, a semiconductor chip borne on a wiring board via an elastic material, which board includes an insulating substrate with a plurality of openings thereon on which a conductive pattern is formed, and by sealing at least one of said openings, wherein
20 a die having a protrusion around an area overlapping said sealed opening is used for a back of the surface of said wiring board which bears said semiconductor chip.